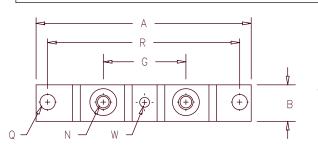
Schottky PowerMod CPT60080 — CPT600100











D=Doubler

Notes: Baseplate: Nickel plated copper

Dim. Inches		Millimeters		
Min.	Max.	Min.	Max.	Notes
A B 0.700 C E 0.120 F 0.490 G 1.375 H 0.050	3.630 0.800 .680 0.130 0.510 BSC	17.78 3.05 12.45 34.92	92.20 20.32 17.28 3.30 12.95 2 BSC	
N Q 0.275 R 3.150 U 0.600 V 0.312 W 0.180	0.290 BSC 0.340 0.195	1.25 6.99 80.0 15.24 7.92 4.57	7.37 1 BSC 8.64 4.95	1/4-20 Dia.

Microsemi Catalog Number	Industry Part Number	J	Repetitive Peak Reverse Voltage
CPT60080*	MBR60080CT	80V	80V

CPT60090* 90V 90V CPT600100* MBR600100CT 100V 100V

*Add Suffix A for Common Anode, D for Doubler

- Schottky Barrier Rectifier
- Guard ring protection
- 600 Amperes/ 80 to 100 Volts
- 175°C junction temperature
- Reverse energy tested
- ROHS Compliant

Electrical Characteristics

F(AV) 600 Amps Average forward current per pkg (AV) 300 Amps Average forward current per leg IFSM 6000 Amps Maximum surge current per leg Maximum repetitive reverse current per leg ^IR(OV) 2 Amps Max peak forward voltage per lea VFM 0.85 Volt 0.85 Volts Max peak forward voltage per leg V_{FM} 0.62 Volts Max peak forward voltage per leg 75 mA ^IRM Max peak reverse current per leg ^IRM Max peak reverse current per leg 8.0 mA Typical junction capacitance per leg 9000 pF

 ^{T}C = 132°C, Square wave, $^{R}\Theta$ JC = 0.10°C/W ^{T}C = 132°C, Square wave, $^{R}\Theta$ JC = 0.20°C/W 8.3ms, half sine, ^{T}J = 175°C f = 1 KHZ, 25°C, 1µsec square wave I FM = 300A: ^{T}J = 25°C I FM = 300A: ^{T}J = 175°C V RRM, ^{T}J = 125°C* V RRM, ^{T}J = 25°C V R = 5.0V, ^{T}C = 25°C

*Pulse test: Pulse width 300 µsec, Duty cycle 2%

Thermal and Mechanical Characteristics

Storage temp range
Operating junction temp range
Max thermal resistance per leg
Max thermal resistance per pkg
Typical thermal resistance (greased)
Terminal Torque
Mounting Base Torque (outside holes)
Mounting Base Torque (center hole)
center hole must be torqued first
Weight

2.8 ounces (78 grams) typical



CPT60080 - CPT600100

Figure 1 Typical Forward Characteristics — Per Leg

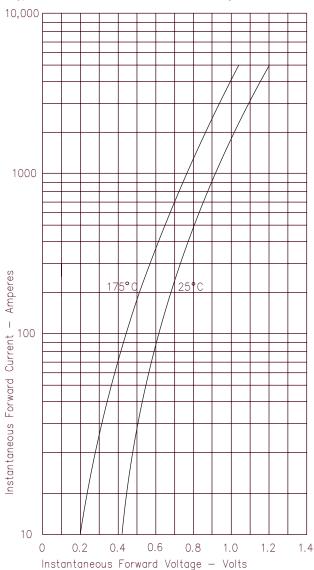


Figure 2 Typical Reverse Characteristics — Per Leg

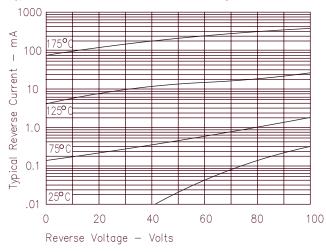


Figure 3 Typical Junction Capacitance — Per Leg

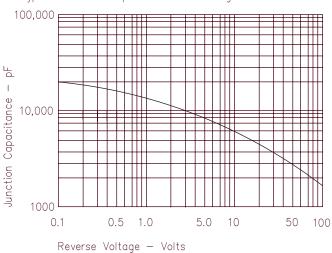
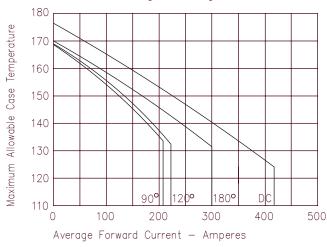
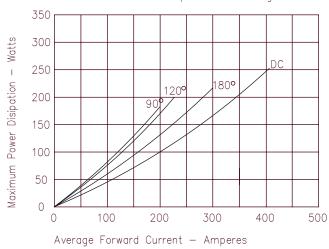


Figure 4
Forward Current Derating — Per Leg



Maximum Forward Power Dissipation — Per Leg





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